

## FEATURES

- Metal-on-silicon junction
- Low turn-on voltage
- Ultrafast switching speed
- Primarily intended for high level UHF mixers and ultrafast switching applications
- The diode is also available in the MiniMELF case with type designation LL45.
- High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC

## MECHANICAL DATA

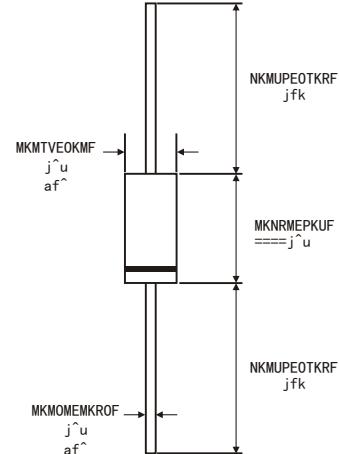
- Case: DO-35 glass case
- *Polarity*: color band denotes cathode end
- *Weight*: Approx. 0.13 gram

## ABSOLUTE RATINGS(LIMITING VALUES)

	Symbols	Value	Units
Peak Reverse Voltage	$V_{RRM}$	15	V
Forward Continuous Current	$I_F$	30	mA
Surge non repetitive forward current $t_p \leq 1s$	$I_{FSM}$	60	mA
Junction and Storage temperature range	$T_{STG}$ $T_J$	-65 to +150 -65 to +125	°C
Maximum Lead Temperature for Soldering during 10s at 4mm from Case	$T_L$	230	°C

## ELECTRICAL CHARACTERISTICS

	Symbols	Min.	Typ.	Max.	Units
Reverse breakdown voltage at $I_R=10\mu A$	$V_R$	15			V
Leakage current at $V_R=6V$	$I_R$			100	nA
Forward voltage drop at $I_F=1mA$ Test pulse: $t_p \leq 300\mu s$ $\delta < 2\%$ $I_F=10mA$ $I_F=30mA$	$V_F$			0.38 0.50 1	V
Junction Capacitance at $V_R=1V$ , $f=1MHz$	$C_J$			1.1	pF
Thermal resistance	$R_{\theta JA}$			400	K/W



Dimensions in inches and (millimeters)

## RATINGS AND CHARACTERISTIC CURVES

Figure 1. Forward current versus forward voltage at different temperatures(typical values)

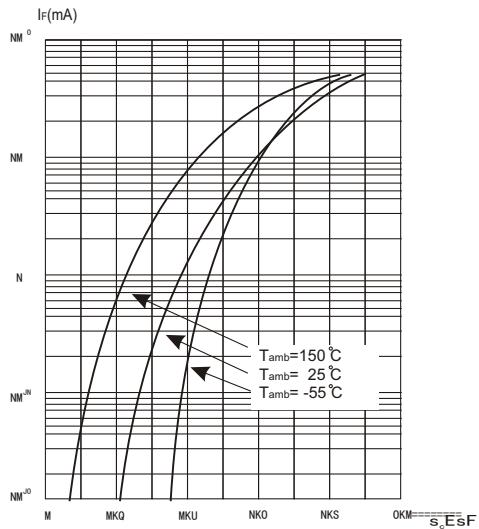


Figure 3. Reverse current versus ambient temperature

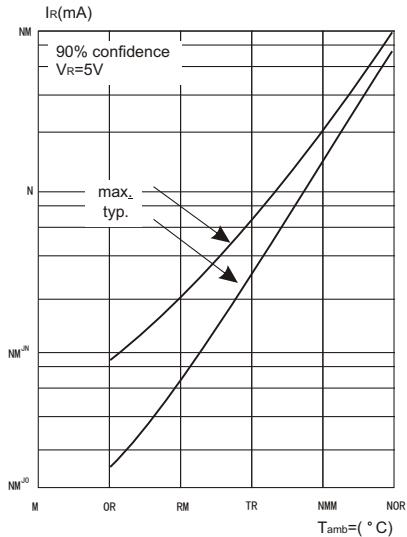


Figure 2 Capacitance CJ versus reverse applied voltage VR (typical values)

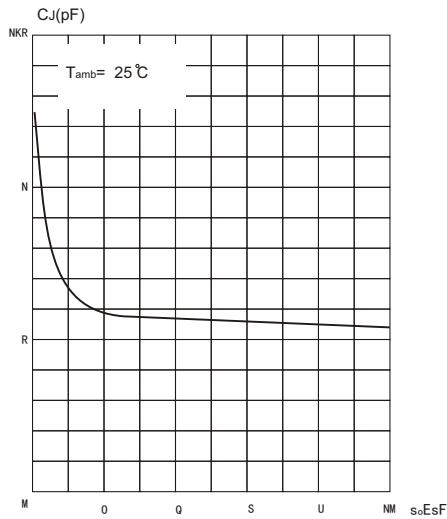


Figure 4. Reverse current versus continuous reverse voltage (typical values)

